

**PCIM Europe 2026**  
**Toshiba Electronics Europe GmbH**  
**Hall 4A, Booth 4A-227**



### **Toshiba to Showcase Advanced Power Electronics Innovations to Support Electrification at PCIM Europe 2026**

Next-generation SiC modules, high-power IEGT devices, and expert-led sessions to drive efficiency, power density and sustainability across key industries

**Düsseldorf, Germany, 28<sup>th</sup> May 2026** – Toshiba Electronics Europe GmbH is showcasing its latest power electronics innovations at PCIM Europe 2026 in Nuremberg, Germany, June 9 to 11, Hall 4A, Booth 4A-227. Guided by its '*Excellence in Power*' philosophy, Toshiba continues to support engineers across Europe with robust, high-performance solutions that enhance efficiency, power density and system reliability on the path toward an all-electric society.

Toshiba's presence at PCIM reflects its ongoing focus on power semiconductors and associated system solutions. The company has aligned its portfolio around key application areas and continues to invest in technologies that support evolving requirements in electrified transport, industrial power systems, renewable energy generation, and AI-driven data centre and future DC grid infrastructure.

At the event, Toshiba will highlight its latest technologies, including next-generation SiC MOSFET technology and modules delivering significant reductions in on-resistance and switching losses, enabling more efficient, compact high-frequency inverter systems. The company's new 6500V/2000A Press Pack IEGT devices are designed for high-voltage systems. Key applications for these two products include railway traction, power grids, heavy industry, electric vehicles, and large-scale renewable energy and HVAC systems.

Visitors to the booth will be able to explore a range of supporting technologies, including gate driver, isolation, and system protection reference designs for high-voltage applications, as well as complete inverter, motor control, and HVAC demonstration platforms. The company will also highlight its SiC and super-junction MOSFET-based power-supply solutions for AI servers, fast chargers, and telecom infrastructure.

In addition, Toshiba will provide insights into advanced packaging concepts, wafers, bare dies, and module mock-ups for automotive applications, alongside rapid prototyping solutions using software tools and MIKROE Click boards™. Automotive-ready BLDC/DC motor drivers and gate drivers, available with and without MCUs, will also be on display.

“Many of the systems our customers are developing are expected to operate reliably over long lifecycles,” said Matthias Diephaus, General Manager of Semiconductor Product Marketing, Toshiba Electronics Europe GmbH. “Our approach is to provide stable device platforms, clear product roadmaps, and the engineering support needed to implement them effectively. Ongoing investment in manufacturing and collaboration supports that objective.”

In addition to its exhibition presence, Toshiba experts will contribute to the PCIM conference programme with several technical presentations:

- **[Increasing the Density of Power Supplies for AI Server or Charger with SMD SiC MOSFETs](#)**  
*Wednesday, 10 June 2026 | 15:50 | Exhibitor Stage, Hall 4A, 320*
- **[6500 V-Class PPI Using 2nd Generation Trench-IEGTs](#)**  
*Thursday, 11 June 2026 | 10:10 | Stage: Istanbul, Level 2 (IGBT Technologies)*
- **[Efficient High-Frequency Inverter Operation of Power Module with Advanced SBD-Embedded SiC MOSFET](#)**  
*Thursday, 11 June 2026 | 15:00 | Stage: St. Petersburg, Level 2 (SiC MOSFETs II)*

Toshiba’s experts will be available throughout the event to discuss how these technologies can support the next generation of power system design.

For more information, please visit: [https://toshiba.semicon-storage.com/eu/company/exhibition/articles/exhibition\\_PCIM2026.html](https://toshiba.semicon-storage.com/eu/company/exhibition/articles/exhibition_PCIM2026.html)

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#### **About Toshiba Electronics Europe**

[Toshiba Electronics Europe GmbH](#) (TEE) offers European consumers and businesses a wide variety of hard disk drive (HDD) products plus semiconductor solutions for automotive, industrial, IoT, motion control, telecoms, networking, consumer and white goods applications. Next to HDDs, the company’s broad portfolio encompasses power semiconductors and other discrete devices ranging from diodes to logic ICs, optical semiconductors as well as microcontrollers and application specific standard products (ASSPs)

amongst others. In addition, TEE offers SCiB™ battery cells and modules with lithium titanium oxide (LTO) for heavy-duty applications.

TEE has its headquarters in Düsseldorf, Germany, with branch offices in France, Italy, Spain, Sweden and the United Kingdom providing marketing, sales and logistics services.

Visit Toshiba's websites at [www.toshiba.semicon-storage.com](http://www.toshiba.semicon-storage.com) and [www.scib.jp/en](http://www.scib.jp/en) for further company and product information.

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